

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-10 (Canceled)

11. (currently amended) A circuit board comprising:

a substrate;

a plurality of screen-printed patterns formed on said substrate, each of said screen-printed patterns including at least one of a passive device ~~such as a capacitor element and/or~~ an active device ~~such as an electromechanical conversion element~~; and

a gap disposed between said plurality of screen-printed patterns, wherein said gap is not more than 40 μm .

12. (previously presented) The circuit board according to claim 11, wherein:

said plurality of screen-printed patterns are formed in an aligned manner on said substrate;

a difference between an average thickness of odd-numbered patterns and an average thickness of even-numbered patterns is not more than 5% of an overall average thickness.

13. (previously presented) The circuit board according to claim 11, wherein each of said screen printed patterns comprises a printing ink material applied on said substrate by a mask including a positive pattern section and a negative pattern section with a mask material formed on said negative pattern section, wherein said printing ink material is transferred to

said substrate via openings of a mesh disposed at said positive pattern section, and wherein:
said negative pattern section of said mesh selectively has a mesh opening ratio which is
smaller than an opening ratio of said positive pattern section.

14. (previously presented) The circuit board according to claim 13, wherein a plating layer is formed on said mesh of said negative pattern section of said mask, wherein said plating layer has a thickness of 1 to 20 μm , and wherein said printing ink is not applied to said substrate corresponding to positions on said mask where said plating layer is formed.

15. (canceled)

16. (previously presented) The circuit board according to claim 11, wherein said plurality of screen-printed patterns comprises a single screen-printed layer on said substrate formed by a one time screen printing application.

17. (previously presented) The circuit board according to claim 11, wherein:
said plurality of screen-printed patterns are formed in an aligned manner on said substrate; and
a difference between thicknesses of two adjacent patterns is not more than 5% of an overall average thickness.